

### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDSON	ID
40V	3.3mΩ	100A

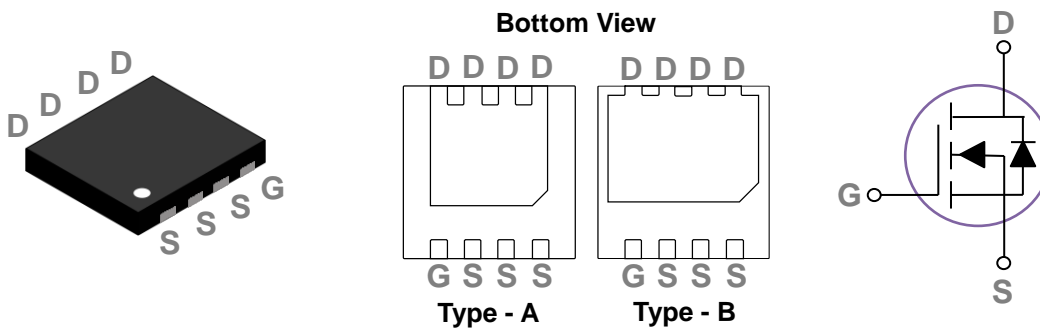
### Features

- Improved dv/dt capability
- Fast switching
- Green Device Available

### Applications

- Motor Drive
- Power Tools
- LED Lighting
- Quick Charger

### DFN3.3X3.3 Pin Configuration



### Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )	100	A
	Drain Current – Continuous ( $T_c=100^\circ\text{C}$ )	63	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	400	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	168	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	58	A
$P_D$	Power Dissipation ( $T_c=25^\circ\text{C}$ )	63.5	W
	Power Dissipation – Derate above $25^\circ\text{C}$	0.51	W/ $^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	1.97	$^\circ\text{C}/\text{W}$

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	40	---	---	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	μA
		V <sub>DS</sub> =32V, V <sub>GS</sub> =0V, T <sub>J</sub> =100°C	---	---	10	μA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA

**On Characteristics**

R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =25A	---	2.7	3.3	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250μA	2	3	4	V

**Dynamic and switching Characteristics**

Q <sub>g</sub>	Total Gate Charge <sup>3, 4</sup>	V <sub>DS</sub> =20V, V <sub>GS</sub> =10V, I <sub>D</sub> =50A	---	30	45	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>3, 4</sup>		---	5.5	10	
Q <sub>gd</sub>	Gate-Drain Charge <sup>3, 4</sup>		---	9.5	15	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>3, 4</sup>	V <sub>DD</sub> =20V, V <sub>GS</sub> =10V, R <sub>G</sub> =6Ω I <sub>D</sub> =50A	---	10	15	ns
T <sub>r</sub>	Rise Time <sup>3, 4</sup>		---	10	15	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>3, 4</sup>		---	28	45	
T <sub>f</sub>	Fall Time <sup>3, 4</sup>		---	16	25	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, F=1MHz	---	1700	2500	pF
C <sub>oss</sub>	Output Capacitance		---	750	1200	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	55	85	
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz	---	0.45	---	Ω

**Guaranteed Avalanche Energy**

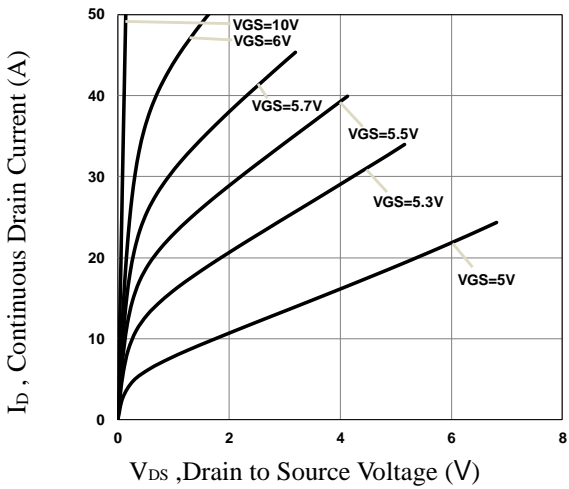
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy	V <sub>DD</sub> =25V, L=0.1mH, I <sub>AS</sub> =38A	72.2	---	---	mJ

**Drain-Source Diode Characteristics and Maximum Ratings**

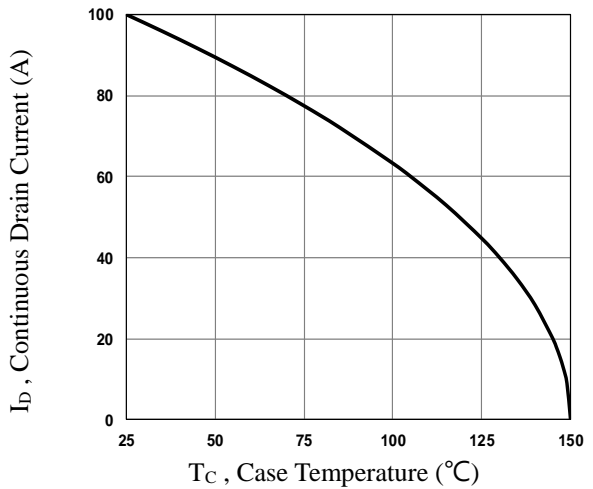
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	100	A
I <sub>SM</sub>	Pulsed Source Current		---	---	200	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	---	---	1	V
T <sub>rr</sub>	Reverse Recovery Time	V <sub>R</sub> =30V, I <sub>S</sub> =10A	---	55	---	ns
Q <sub>rr</sub>	Reverse Recovery Charge	di/dt=100A/μs T <sub>J</sub> =25°C	---	60	---	nC

Note :

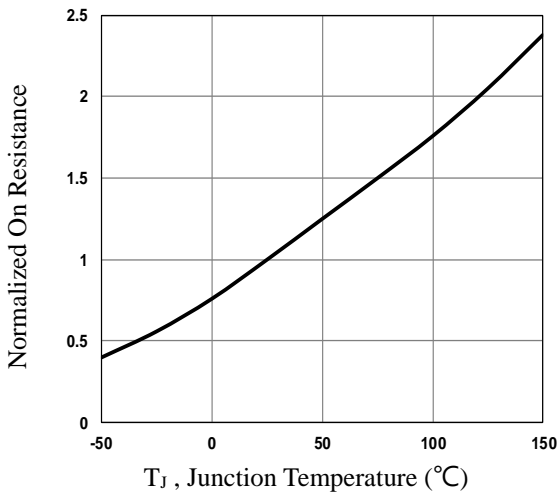
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V<sub>DD</sub>=25V, V<sub>GS</sub>=10V, L=0.1mH, I<sub>AS</sub>=58A, R<sub>G</sub>=25Ω, Starting T<sub>J</sub>=25°C.
3. The data tested by pulsed, pulse width ≤ 300μs, duty cycle ≤ 2%.
4. Essentially independent of operating temperature.



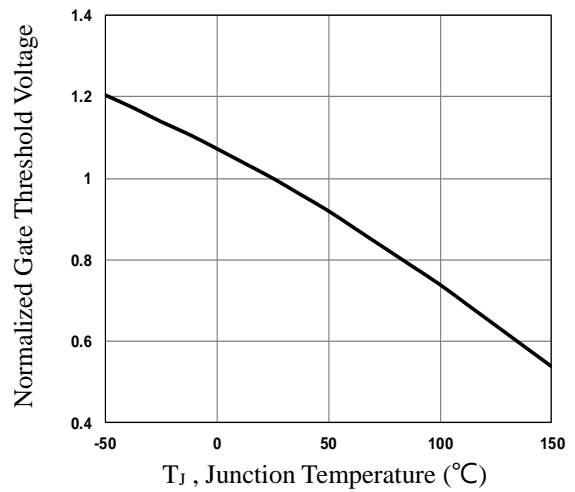
**Fig.1 Typical Output Characteristics**



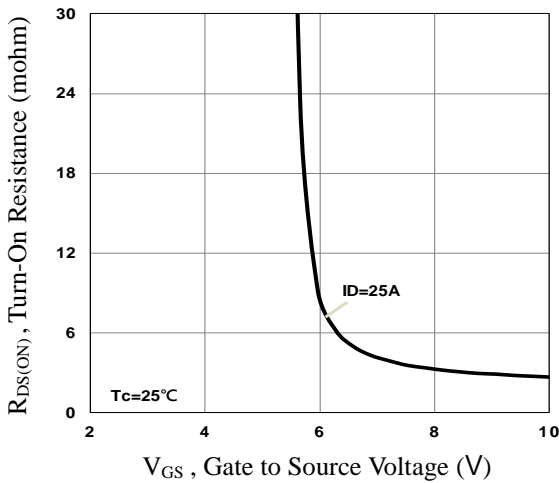
**Fig.2 Continuous Drain Current vs.  $T_C$**



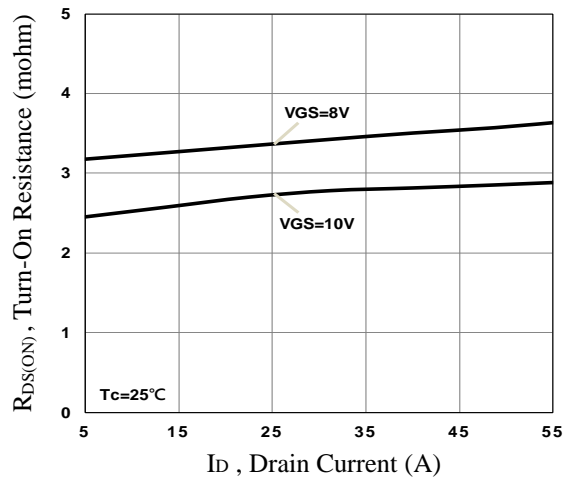
**Fig.3 Normalized  $R_{DS(on)}$  vs.  $T_J$**



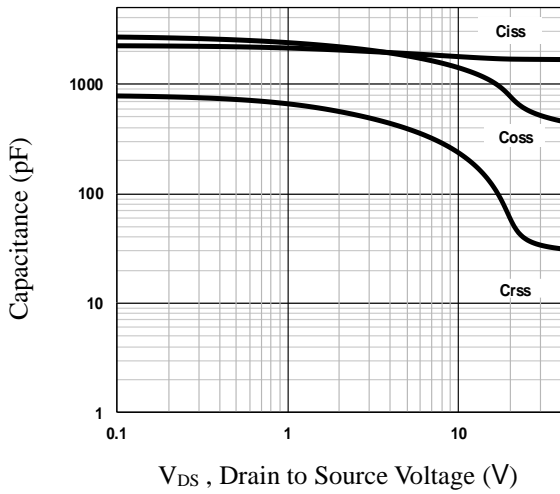
**Fig.4 Normalized  $V_{th}$  vs.  $T_J$**



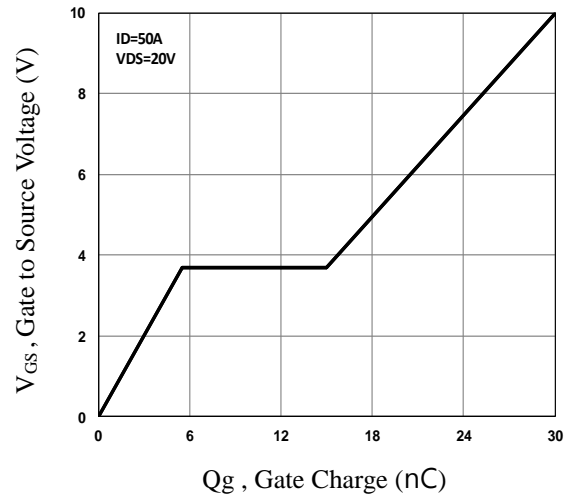
**Fig.5 Turn-On Resistance vs.  $V_{GS}$**



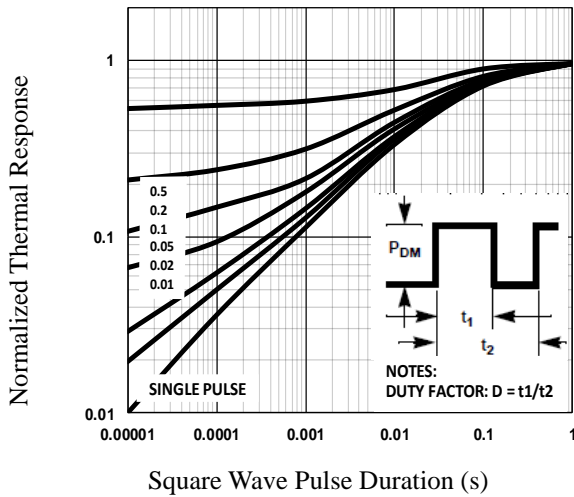
**Fig.6 Turn-On Resistance vs.  $I_D$**



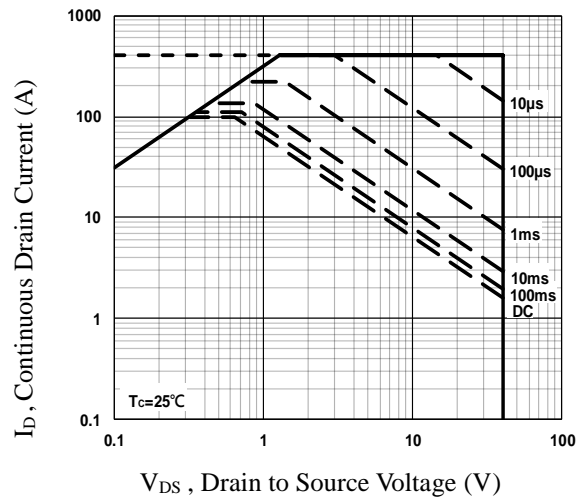
**Fig.7 Capacitance Characteristics**



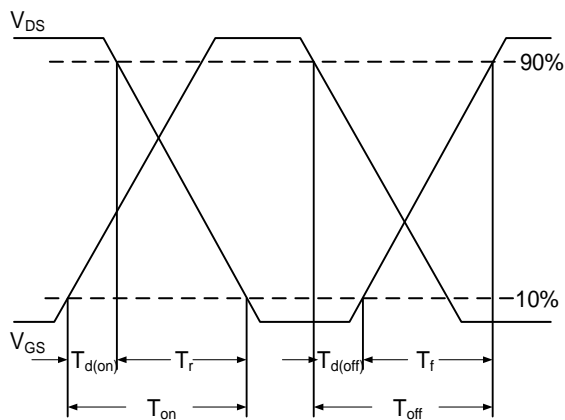
**Fig.8 Gate Charge Characteristics**



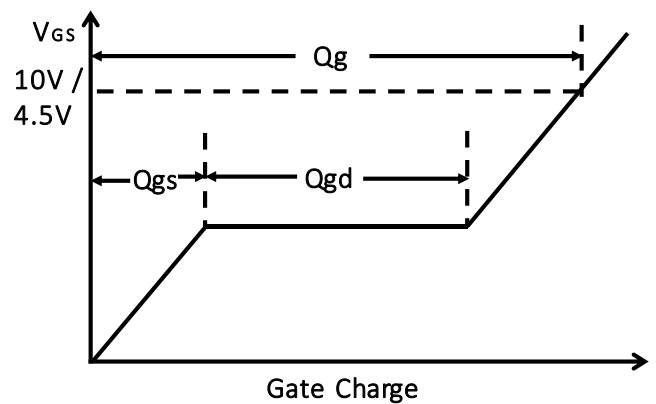
**Fig.9 Normalized Transient Impedance**



**Fig.10 Maximum Safe Operation Area**



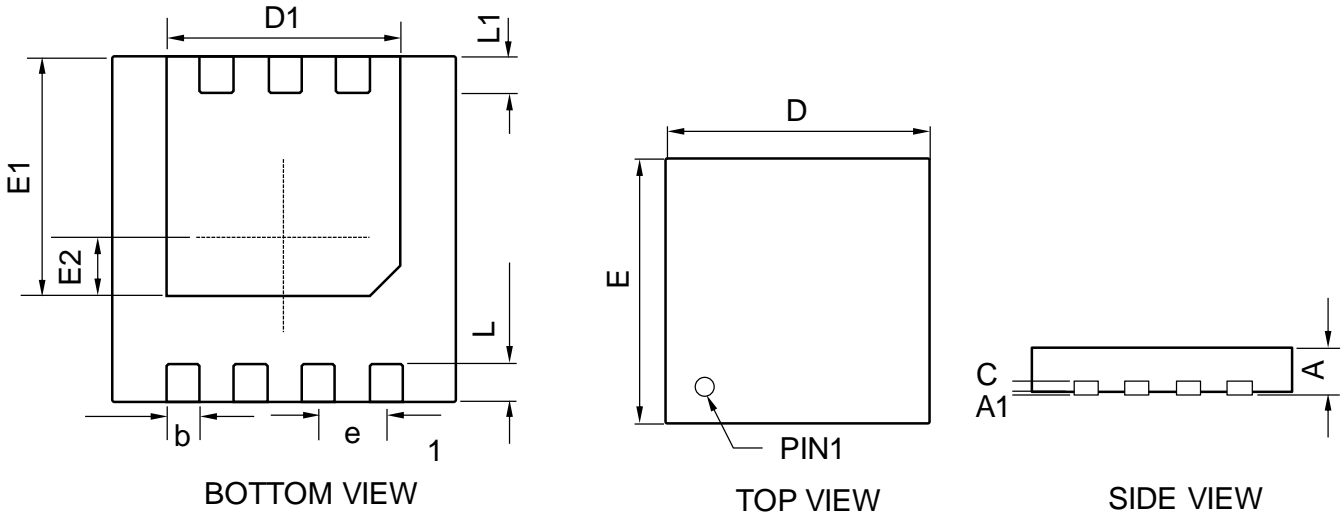
**Fig.11 Switching Time Waveform**



**Fig.12 Gate Charge Waveform**

## DFN3.3X3.3 PACKAGE INFORMATION

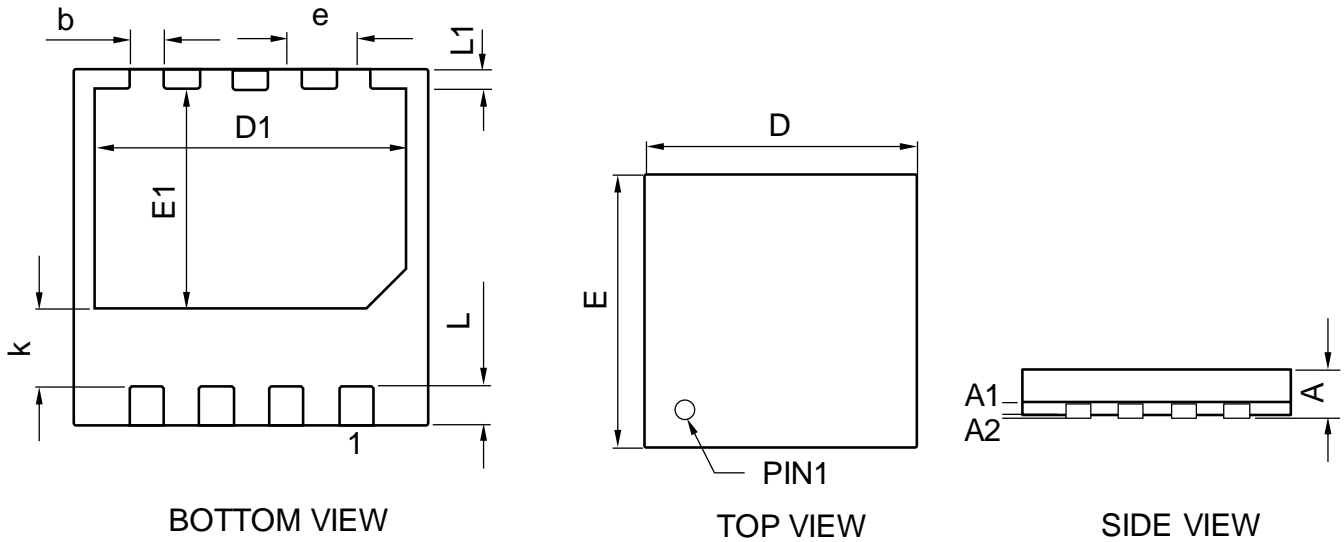
Type - A



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.800	0.700	0.031	0.028
A1	0.050	---	0.010	---
C	0.250	0.150	0.010	0.006
D	3.400	3.200	0.134	0.126
D1	2.350	2.150	0.093	0.085
E	3.400	3.200	0.134	0.126
E1	2.350	2.100	0.093	0.083
E2	0.680	0.480	0.027	0.019
b	0.350	0.240	0.014	0.009
L	0.500	0.300	0.020	0.012
L1	0.450	0.250	0.018	0.010
e	0.650BSC		0.026BSC	

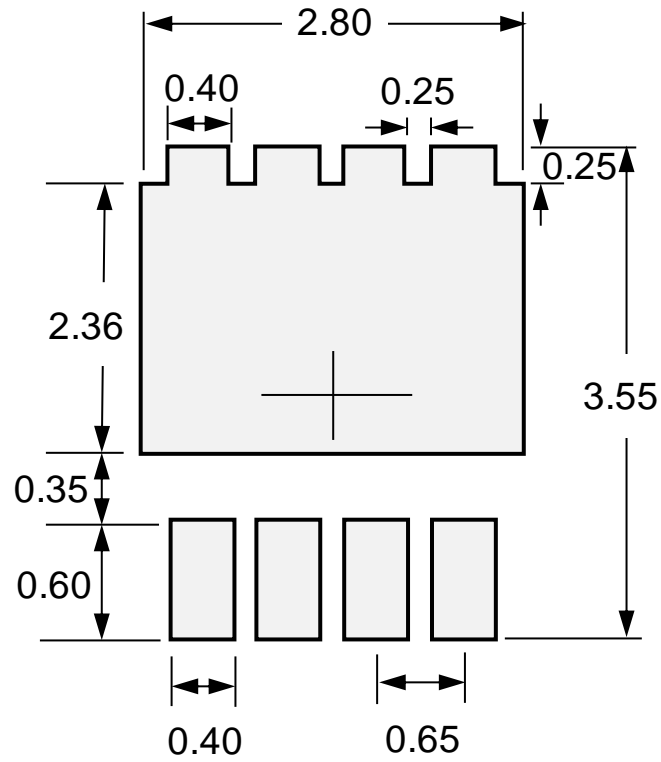
**DFN3.3X3.3 PACKAGE INFORMATION**

Type - B



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.800	0.700	0.031	0.028
A1	0.250	0.150	0.010	0.006
A2	0.050	---	0.002	---
D	3.400	3.200	0.134	0.126
E	3.400	3.200	0.134	0.126
D1	2.850	2.650	0.112	0.104
E1	2.250	2.000	0.089	0.079
b	0.400	0.250	0.016	0.010
L	0.600	0.400	0.024	0.016
L1	0.350 BSC		0.014 BSC	
k	0.500	0.250	0.020	0.010
e	0.65BSC		0.026BSC	

### DFN3.3X3.3 RECOMMENDED LAND PATTERN



unit : mm